



SOT459-2

LQFP208, plastic, low profile quad; flat leaded package; 208 terminals; 0.5 mm pitch; 28 mm x 28 mm x 1.6 mm body

31 March 2017

Package information

1. Package summary

| | |
|--------------------------------|--------------------------------------|
| Terminal position code | Q (quad) |
| Package type descriptive code | LQFP208 |
| Package type industry code | LQFP208 |
| Package style descriptive code | LQFP (low profile quad flat package) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 24-3-2017 |
| Manufacturer package code | 98ASS23458W |

Table 1. Package summary

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|--|-----|-----|-----|-----|------|
| D | package length | | - | - | 28 | - | mm |
| E | package width | | - | - | 28 | - | mm |
| A | seated height | | - | - | 1.6 | - | mm |
| e | nominal pitch | | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | | - | - | 208 | - | |



2. Package outline

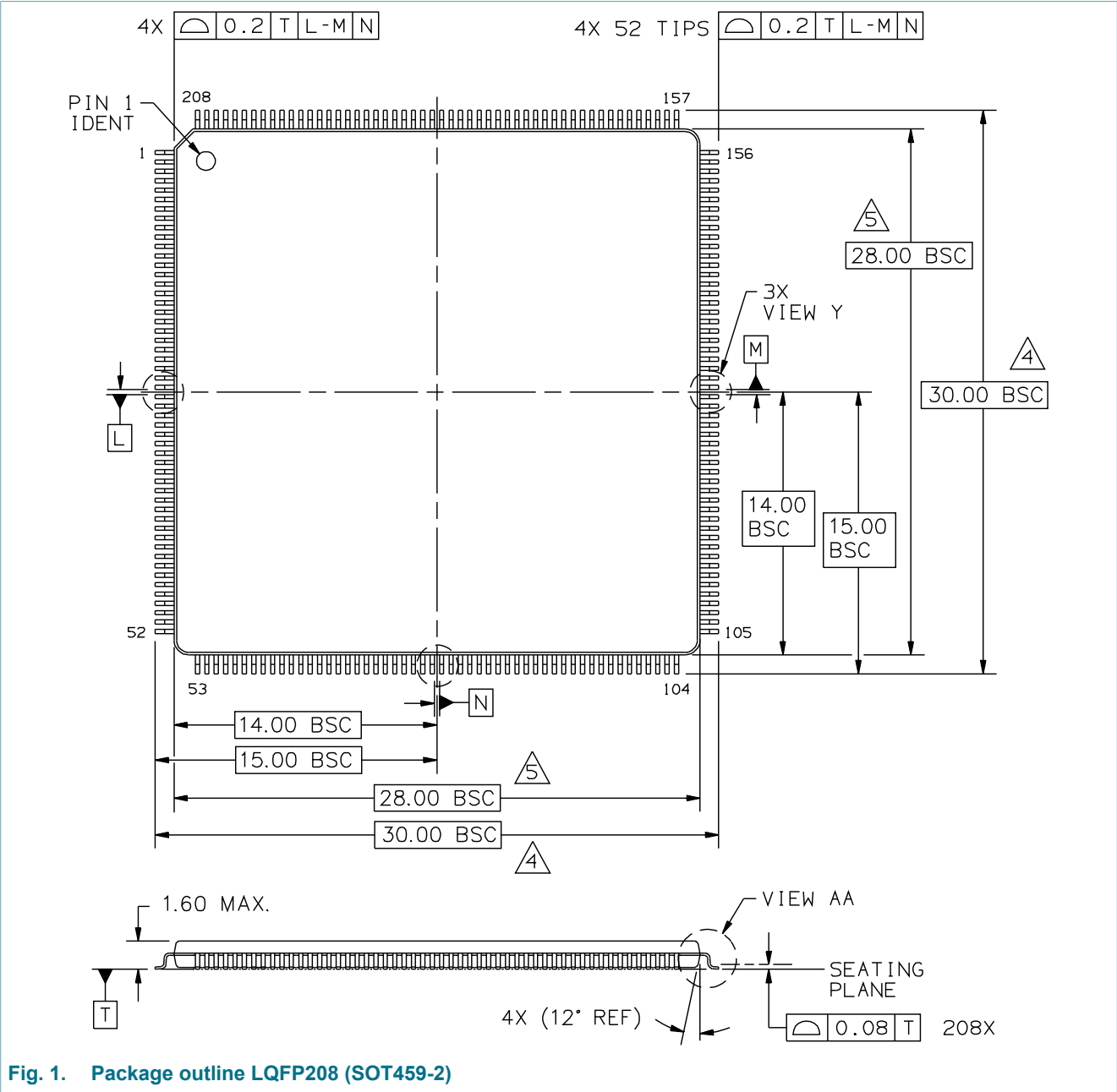
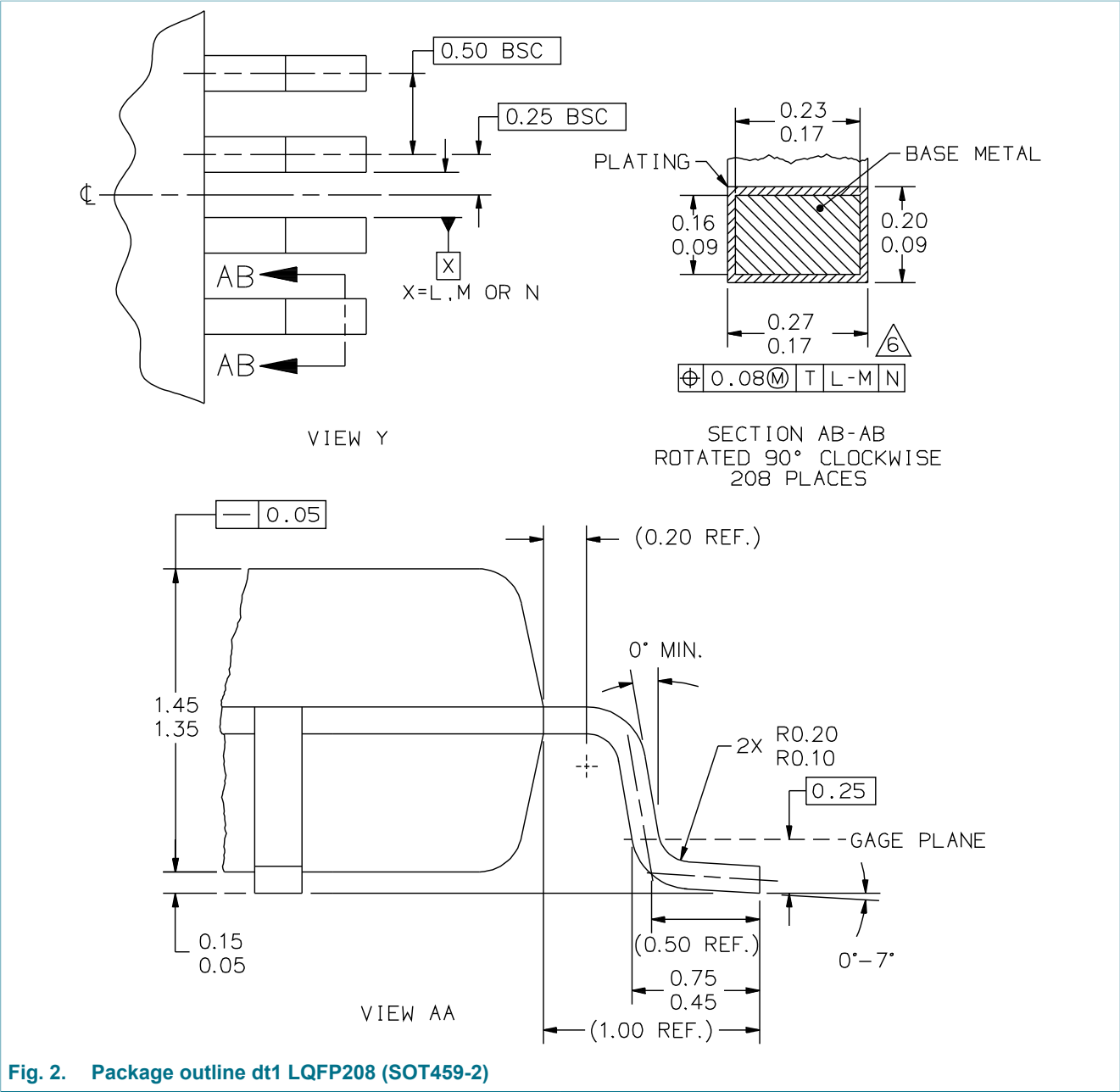


Fig. 1. Package outline LQFP208 (SOT459-2)



LQFP208, plastic, low profile quad; flat leaded package; 208 terminals; 0.5 mm pitch; 28 mm x 28 mm x 1.6 mm body

NOTES

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS IN MILLIMETERS.
3. DATUMS L, M AND N TO BE DETERMINED AT THE SEATING PLANE, DATUM T.



DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM T.



DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS INCLUDE MOLD MISMATCH.



DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD 0.07.

Fig. 3. Package outline note LQFP208 (SOT459-2)

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3. Legal information

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